AMENDMENTS TO THE CLAIMS

1. (Currently amended) A peroxide curable silicon adhesive composition comprising

20 to 80 parts by weight of a diorganopolysiloxane (A), represented by any one of the following formulae,

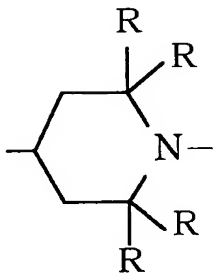
$R^2_3SiO-(R^2_2SiO)_p-SiR^2_3$

$R^2_2(HO)SiO-(R^2_2SiO)_p-SiR^2_2(OH)$

wherein R^2 may be the same with or different from each other and is a hydrocarbon group having 1 to 10 carbon atoms, and p is such a number that a viscosity at 25 °C of component (A) is 500 mPa·s or higher,

80 to 20 parts by weight of a polyorganosiloxane (B) comprising $R^1_3SiO_{0.5}$ unit and SiO_2 unit in a molar ratio of the $R^1_3SiO_{0.5}$ unit to the SiO_2 unit of from 0.6 to 1.7, wherein R^1 is a monovalent hydrocarbon group having 1 to 10 carbon atoms,

0.01 to 1.0 part by weight, based on a total of (A) and (B) of 100 parts by weight, of a hindered amine moiety (C) having the molecular structure represented by the following formula,



wherein R is a monovalent hydrocarbon group having 1 to 6 carbon atoms, and

0.1 to 5.0 parts by weight, based on a total of (A) and (B) of 100 parts by weight, of an organic peroxide (D).

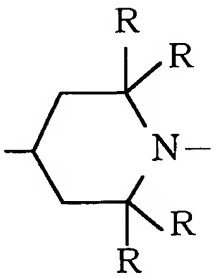
2. (Original) The peroxide curable silicon adhesive composition according to claim 1, wherein the diorganopolysiloxane (A) comprises 1 to 35 mole % of diphenylsiloxy unit.

3. (Currently Amended) An addition-reactive silicon adhesive composition comprising

20 to 80 parts by weight of a diorganopolysiloxane (A') having 2 or more alkenyl groups and a viscosity of at least 1,000 mPa·s in the case that the diorganopolysiloxane (A') is oily at 25 °C, or at most 100,000 mPa·s in a 30 wt% solution in toluene in the case that the diorganopolysiloxane (A') is gummy at 25 °C,

80 to 20 parts by weight of a polyorganosiloxane (B) comprising $R^1{}_3SiO_{0.5}$ unit and SiO_2 unit in a molar ratio of the $R^1{}_3SiO_{0.5}$ unit to the SiO_2 unit of from 0.6 to 1.7, wherein R^1 is a monovalent hydrocarbon group having 1 to 10 carbon atoms,

0.01 to 1.0 part by weight, based on a total of (A') and (B) of 100 parts by weight, of a hindered amine moiety (C) having the molecular structure represented by the following formula,



a polyorganosiloxane (E)having SiH group in such an amount that a molar ratio of the SiH group to the alkenyl group of the component(A') ranges from 0.5 to 20,

0 to 8.0 part by weight, based on a total of (A') and (B) of 100 parts by weight, of a retarder (F), and

a platinum catalyst (G) in such an amount that an amount as platinum ranges from 1 to 5000 ppm based on a total of (A') and (B) of 100 parts by weight.

4. (Original) The addition-reactive silicon adhesive according to claim 3, wherein the diorganopolysiloxane (A') comprises 1 to 35 mole % of diphenylsiloxy unit.

5. (Original) The addition-reactive silicon adhesive according to claim 3, wherein the composition further comprises 0.1 to 10 parts by weight, based on a total of (A') and (B) of 100 parts by weight, of a phenolic antioxidant (H).

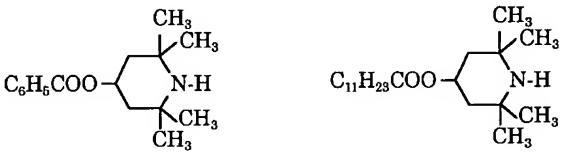
6. (Original) An adhesive tape comprising a plastic film and an adhesive applied on at least one side of the plastic film, the adhesive being made by curing the adhesive composition according to claim 1 or 3.

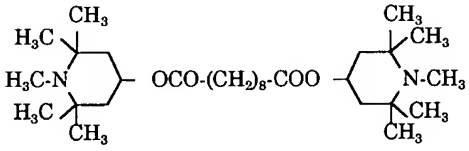
7. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein the diorganopolysiloxane (A) has a viscosity at 25 °C of 10,000 mPa·s or higher.

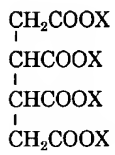
8. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein the polyorganosiloxane (B) has an OH group in an amount of 4.0 wt % or smaller based on a total weight of the polyorganosiloxane (B).

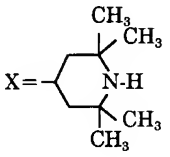
9. (New) The addition-reactive silicon adhesive composition according to claim 3, wherein the polyorganosiloxane (B) has an OH group in an amount of 4.0 wt % or smaller based on a total weight of the polyorganosiloxane (B).

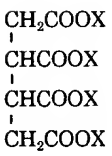
10. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein the hindered amine moiety (C) is at least one compound selected from the group consisting of

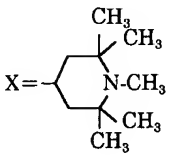


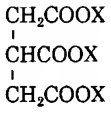


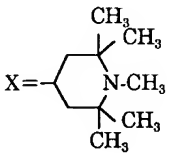


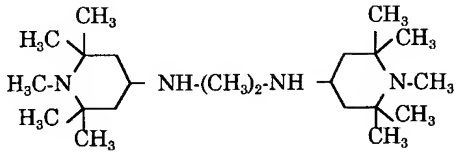


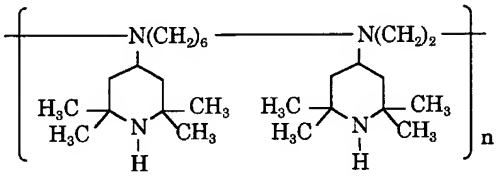


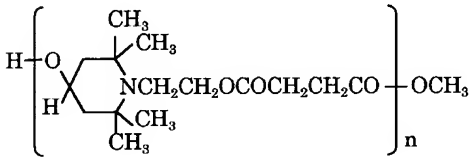












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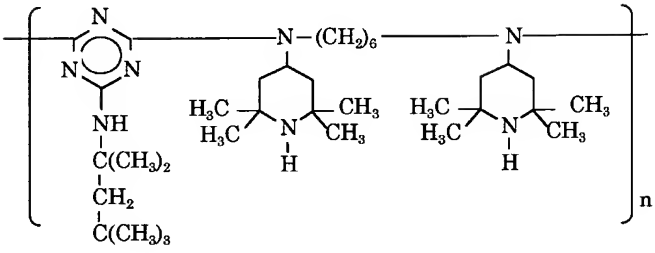
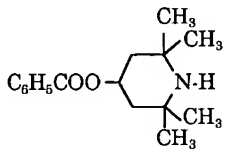
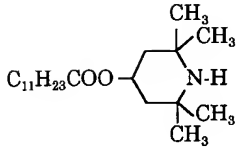
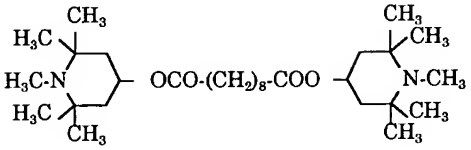
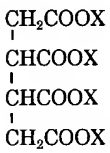


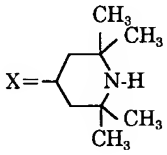
11. (New) The addition-reactive silicon adhesive composition according to claim 3, wherein the hindered amine moiety (C) is at least one compound selected from the group consisting of

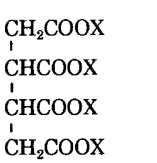


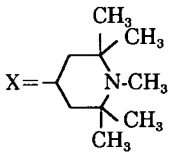


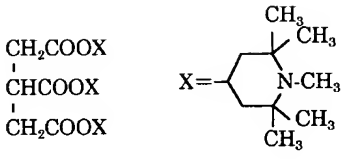


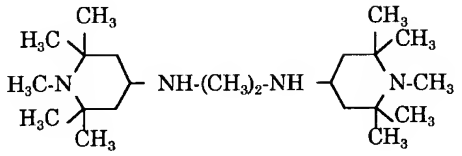


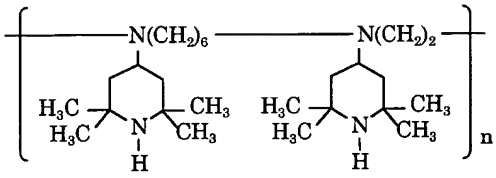


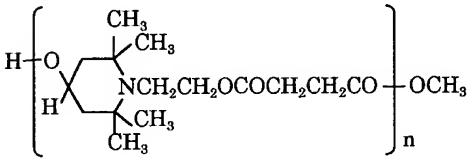












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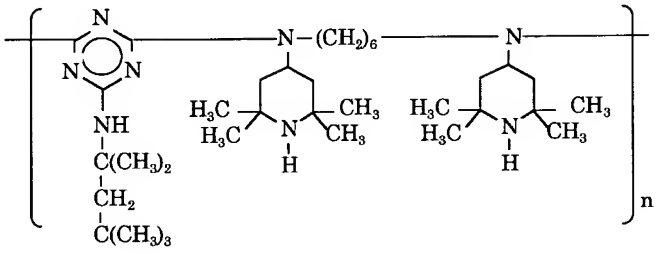

12. (New) The peroxide curable silicon adhesive composition according to claim 1, wherein no residue is left when the adhesive composition is heated up to 280 °C.

13. (New) The addition-reactive silicon adhesive composition according to claim 3, wherein no residue is left when the adhesive composition is heated up to 280 °C.